

# NTC Thermistor SMD



## FEATURES

- Multilayer structure allows diverse resistance value in the same B constant
- Multilayer structure allows lower resistance at high B constant.
- Solder plating with Ni barrier gives high reliability for both flow and reflow soldering.
- Unified shape and tightly controlled dimension is fit to high mounting speed.

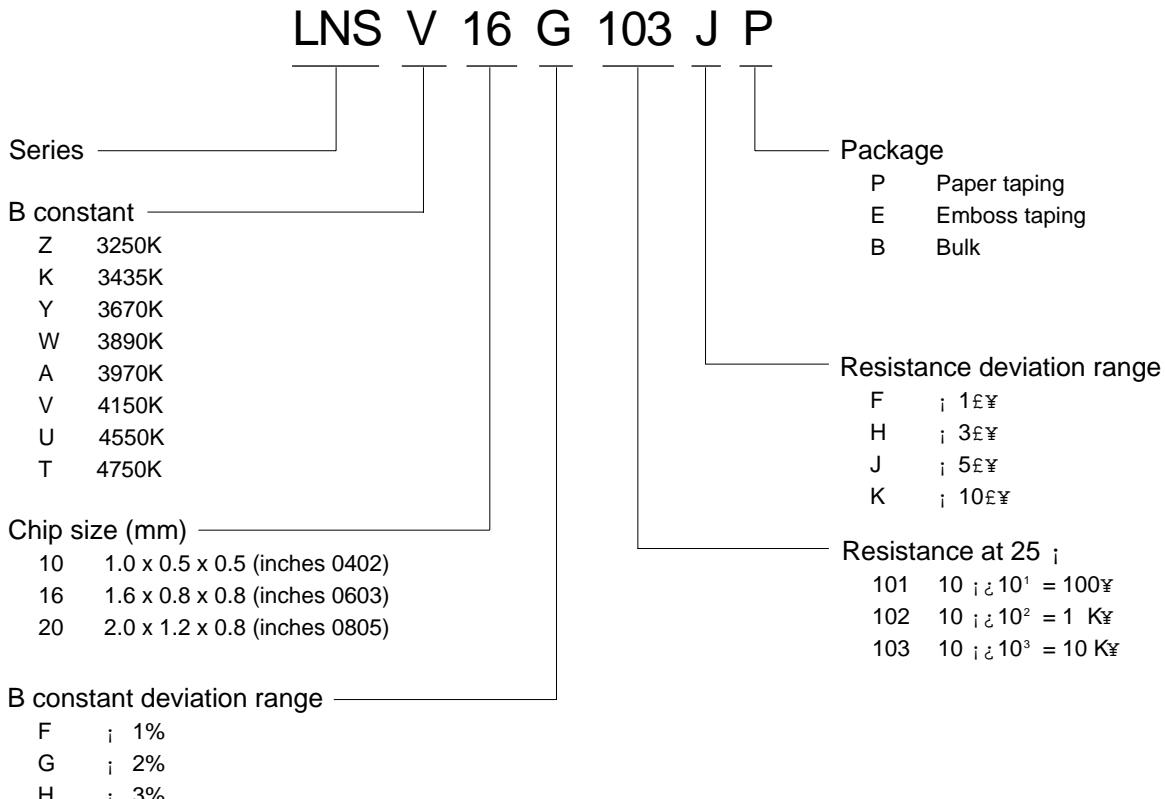
## DESCRIPTION

The LNS series is manganese oxide based NTC thermistor, which shows non-linear resistance-temperature behavior. Multilayered structure has as high reliability as monoblock type, even without protective glass coating, since the active electrode and sensor layer is buried inside the ceramic body.

## APPLICATIONS

- Temperature compensation for crystal oscillator (TCXO)
- Temperature compensation for Personal computer
- Temperature detection for CPU and memory device
- Temperature detection for battery pack
- Temperature compensation for contrast of LCD

## ORDERING INFORMATION



# NTC Thermistor SMD

## SPECIFICATIONS

1005(0402) size

Part Number	Resistance @ 25°C	B constant 25/85	Dissipation Constant	Maximum Power Rating	Operating Temp.
LNSZ10_220_	22Ω	3250K	1mW/°C	100mW	-40~85 °C
LNSZ10_300_	30Ω	3250K			
LNSZ10_400_	40Ω	3250K			
LNSZ10_450_	45Ω	3250K			
LNSZ10_500_	50Ω	3250K			
LNSZ10_600_	60Ω	3250K			
LNSZ10_101_	100Ω	3250K			
LNSK10_502_	5Ω	3435K			
LNSK10_103_	10Ω	3435K			
LNSY10_102_	1Ω	3670K			
LNSY10_222_	2.2Ω	3670K	1mW/°C	100mW	-40~125°C
LNSY10_472_	4.7Ω	3670K			
LNSY10_502_	5Ω	3670K			
LNSY10_682_	6.8Ω	3670K			
LNSY10_103_	10Ω	3670K			
LNSW10_103_	10Ω	3890K			
LNSW10_223_	22Ω	3890K			
LNSW10_443_	44Ω	3890K			
LNSV10_202_	2Ω	4150K			
LNSV10_222_	2.2Ω	4150K			
LNSV10_272_	2.7Ω	4150K	1mW/°C	100mW	-40~85°C
LNSV10_332_	3.3Ω	4150K			
LNSV10_103_	10Ω	4150K			
LNSV10_333_	33Ω	4150K			
LNSV10_473_	47Ω	4150K			
LNSV10_503_	50Ω	4150K			
LNSV10_583_	58Ω	4150K			
LNSV10_683_	68Ω	4150K			
LNSV10_853_	85Ω	4150K			
LNSV10_104_	100Ω	4150K			
LNSV10_124_	120Ω	4150K	1mW/°C	100mW	-40~125°C
LNSV10_154_	150Ω	4150K			
LNSV10_334_	330Ω	4150K			
LNSV10_474_	470Ω	4150K			
LNSU10_333_	33Ω	4550K			
LNSU10_683_	68Ω	4550K			
LNSU10_104_	100Ω	4550K			
LNSU10_224_	220Ω	4550K			
LNSU10_105_	1Ω	4750K			
LNST10_474_	470Ω	4750K			
LNSU10_504_	500Ω	4750K	1mW/°C	100mW	-40~85°C
LNSU10_205_	2Ω	4750K			

If you want additional spec., please contact to lattron. Fax : 82-42-935-2034 Email : lattron@lattron.com

### Resistance @ 25°C

The zero-power resistance at the standard temperature of 25°C. The zero-power resistance means the value of DC resistance of a thermistor measured at a specified temperature, with electric load being kept so small that there is no noticeable change in the measured resistance by the influence of the applied electric load.

### Bconstant 25 / 85

$B = \ln(R_{25}/R_85) / (1/T_{25} - 1/T_{85})$  Without special note, B constant is calculated from the resistance values at 25°C and 85°C [B25/85], which is the most common.

### Dissipation constant ( $\gamma$ )

Dissipation factor is defined as the ratio at a specified ambient temperature of a change in power dissipation in a thermistor to the resultant body temperature change.

$\gamma = P(T_{amb} - 25°C) / P$  mW/°C      ; P : dissipated power      ; T1 : thermistor temp, 85 ; 0.1°C

### Maximum power rating P

This is the maximum handling power, keeping its temperature not exceeding the allowed maximum temperature for operation.

$P_{max} = \gamma(T_{max} - T_a)$  ;  $\gamma$  : dissipation constant ;  $T_a$ : 25°C ;  $T_{max}$ : 125°C

### Thermal Time Constant

The time necessary for an unloaded thermistor to vary its temperature by 63.2% of the difference between its initial and final temperatures. Initial temperature is 85 ; 0.1°C and final temperature is 47.1 ; 0.1°C.

# NTC Thermistor SMD

## 1608(0603) size

Part Number	Resistance @25°C	B constant 25/85	Dissipation Constant	Maximum Power Rating	Operating Temp.
LNSZ16_220_	22Ω	3250K	3mW/°C	300mW	-40~85°C
LNSZ16_300_	30Ω	3250K			
LNSZ16_400_	40Ω	3250K			
LNSZ16_450_	45Ω	3250K			
LNSZ16_500_	50Ω	3250K			
LNSZ16_600_	60Ω	3250K			
LNSZ16_101_	100Ω	3250K			
LNSK16_502_	5Ω	3435K			
LNSK16_103_	10Ω	3435K			
LNSY16_102_	1Ω	3670K			
LNSY16_222_	2.2Ω	3670K	3mW/°C	300mW	-40~125°C
LNSY16_472_	4.7Ω	3670K			
LNSY16_502_	5Ω	3670K			
LNSY16_682_	6.8Ω	3670K			
LNSY16_103_	10Ω	3670K			
LNSW16_103_	10Ω	3890K			
LNSW16_223_	22Ω	3890K			
LNSW16_443_	44Ω	3890K			
LNSV16_202_	2Ω	4150K			
LNSV16_222_	2.2Ω	4150K			
LNSV16_272_	2.7Ω	4150K	3mW/°C	300mW	-40~85°C
LNSV16_332_	3.3Ω	4150K			
LNSV16_103_	10Ω	4150K			
LNSV16_333_	33Ω	4150K			
LNSV16_473_	47Ω	4150K			
LNSV16_503_	50Ω	4150K			
LNSV16_583_	58Ω	4150K			
LNSV16_683_	68Ω	4150K			
LNSV16_853_	85Ω	4150K			
LNSV16_104_	100Ω	4150K			
LNSV16_124_	120Ω	4150K	3mW/°C	300mW	-40~125°C
LNSV16_154_	150Ω	4150K			
LNSV16_334_	330Ω	4150K			
LNSV16_474_	470Ω	4150K			
LNSU16_683_	68Ω	4550K			
LNSU16_104_	100Ω	4550K			
LNSU16_224_	220Ω	4550K			
LNSU16_105_	1Ω	4750K			
LNST16_474_	470Ω	4750K			
LNSU16_504_	500Ω	4750K			
LNSU16_205_	2Ω	4750K			

If you want additional spec., please contact to lattron. Fax : 82-42-935-2034 Email : lattron@lattron.com

### Resistance @ 25°C

The zero-power resistance at the standard temperature of 25°C. The zero-power resistance means the value of DC resistance of a thermistor measured at a specified temperature, with electric load being kept so small that there is no noticeable change in the measured resistance by the influence of the applied electric load.

### Bconstant 25 / 85

$B = \ln(R_2/R_1) / (1/T_2 - 1/T_1)$  Without special note, B constant is calculated from the resistance values at 25°C and 85°C [B25/85], which is the most common.

### Dissipation constant ( $\gamma$ )

Dissipation factor is defined as the ratio at a specified ambient temperature of a change in power dissipation in a thermistor to the resultant body temperature change.

$\gamma = P/(T_2 - 25°C) \text{ mW/}^{\circ}\text{C}$  ;  $P$  : dissipated power ;  $T_2$  : thermistor temp, 85 ; 0.1°C

### Maximum power rating $P$

This is the maximum handling power, keeping its temperature not exceeding the allowed maximum temperature for operation.

$P_{max} = \sqrt{T_{max} - T_a}$  ;  $\gamma$  : dissipation constant ;  $T_a$ :25°C ;  $T_{max}$ :125°C

### Thermal Time Constant

The time necessary for an unloaded thermistor to vary its temperature by 63.2% of the difference between its initial and final temperatures. Initial temperature is 85 ; 0.1°C and final temperature is 47.1 ; 0.1°C.

# NTC Thermistor SMD

## 2012(0805) size

Part Number	Resistance @ 25°C	B constant 25/85	Dissipation Constant	Maximum Power Rating	Operating Temp.
LNSK20_502__	5S	3435K			
LNSK20_103__	10S	3435K			
LNSY20_102__	1S	3670K			
LNSY20_222__	2.2S	3670K			
LNSY20_472__	4.7S	3670K			
LNSY20_502__	5S	3670K			
LNSY20_682__	6.8S	3670K			
LNSY20_103__	10S	3670K			
LNSW20_103__	10S	3890K			
LNSW20_223__	22S	3890K			
LNSW20_443__	44S	3890K			
LNSV20_202__	2S	4150K			
LNSV20_222__	2.2S	4150K			
LNSV20_272__	2.7S	4150K			
LNSV20_332__	3.3S	4150K			
LNSV20_103__	10S	4150K			
LNSV20_333__	33S	4150K			
LNSV20_473__	47S	4150K			
LNSV20_503__	50S	4150K			
LNSV20_583__	58S	4150K			
LNSV20_683__	68S	4150K			
LNSV20_853__	85S	4150K			
LNSV20_104__	100S	4150K			
LNSV20_124__	120S	4150K			
LNSV20_154__	150S	4150K			
LNSV20_334__	330S	4150K			
LNSV20_474__	470S	4150K			
LNSU20_683__	68S	4550K			
LNSU20_104__	100S	4550K			
LNSU20_105__	1S	4750K			
LNST20_474__	470S	4750K			

If you want additional spec., please contact to lattron. Fax : 82-42-935-2034 Email : lattron@lattron.com

### Resistance @ 25°C

The zero-power resistance at the standard temperature of 25°C. The zero-power resistance means the value of DC resistance of a thermistor measured at a specified temperature, with electric load being kept so small that there is no noticeable change in the measured resistance by the influence of the applied electric load.

### Bconstant 25 / 85

$B = \ln(R_2/R_1) / (1/T_2 - 1/T_1)$  Without special note, B constant is calculated from the resistance values at 25°C and 85°C [B25/85], which is the most common.

### Dissipation constant ( $\gamma$ )

Dissipation factor is defined as the ratio at a specified ambient temperature of a change in power dissipation in a thermistor to the resultant body temperature change.

$\gamma = P/(T_2 - 25^\circ\text{C}) \text{ mW}^{-1}\text{°C}$  ;  $P$  : dissipated power ;  $T_2$  : thermistor temp, 85 ;  $0.1^\circ\text{C}$

### Maximum power rating P

This is the maximum handling power, keeping its temperature not exceeding the allowed maximum temperature for operation.

$P_{max} = \gamma(T_{max} - T_a)$  ;  $\gamma$ :dissipation constant ;  $T_a$ :25°C ;  $T_{max}$ :125°C

### Thermal Time Constant

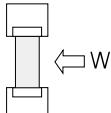
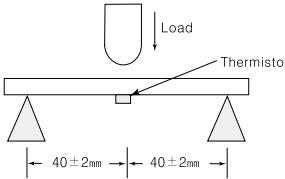
The time necessary for an unloaded thermistor to vary its temperature by 63.2% of the difference between its initial and final temperatures. Initial temperature is 85 ; 0.1°C and final temperature is 47.1 ; 0.1°C.





# NTC Thermistor SMD

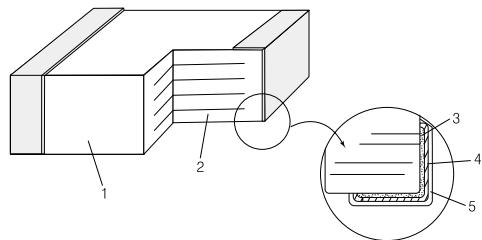
## RELIABILITY TEST METHOD

Item	Test Method	Criteria for judging
Resistance to Soldering Heat Test	Soldering temperature : 260 ; 5°C Duration of immersion : 10 ; 1sec. Preheating : 150 ; , 1min.	Visual : No mechanical damage Zero-power resistance at 25°C Change as against pretest values within ; 3% Change of B-value : within ; 2%
Solderability Test	Soldering temperature : 230 ; 5°C Duration of immersion : 5 ; 1sec. Preheating : 150°C, 1min.	At least 75% of the electrode must be covered with new solder.
Adhesion	Force W is applied to DUT. 	2012 : over 2.0 kg f 1608 : over 1.0 kg f 1005 : over 0.7 kg f
Resistance to flexure of substrate	The middle part of substrate shall, successively, be pressurized by means of the pressurizing rod at a rate of about 1gf/sec. Maintenance time : 5 sec. Bending distance : 1gf 	Visual : No mechanical damage
Dry Heat Test	Test temperature : 125 ; 2°C, 85 ; 2°C (R-T curve Z) Test duration : 1000+48hrs. After completion of the test, leaving the sample under the standard conditions for 24 ; 2hrs.	Zero-power resistance at 25°C: Change as against pretest values within ; 3% Change of B-value : within ; 2%
Cold Test	Test temperature : -30 ; 2°C Test duration : 1000+48hrs. After completion of the test, leaving the sample under the standard conditions for 24 ; 2hrs.	Zero-power resistance at 25°C: Change as against pretest values within ; 3% Change of B-value : within ; 2%
Damp Heat Test (Steady State)	Test temperature : 60 ; 2°C Test relative humidity : 90 ; >95RH% Test duration : 1000+24hrs. After completion of the test, leaving the sample under the standard conditions for 24 ; 2hrs.	Zero-power resistance at 25°C: Change as against pretest values within ; 3% Change of B-value : within ; 2%
Thermal shock Test	+90°C Ordinary temp. -30°C  This cycle is repeated 1000 times. After completion of the test, allow the sample to stand under the standard conditions for at 24 ; 2hrs.	Zero-power resistance at 25 ; : Change as against pretest values within ; 3% Change of B-value : within ; 2%

# Structure and Dimension

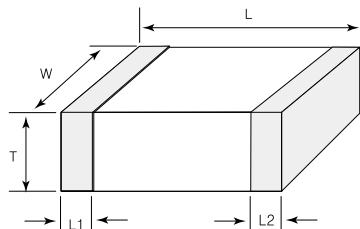
---

## CHIP STRUCTURE



Number	Name
1	Ceramics
2	Inner Electrode
3	External Electrode(Ag)
4	Electroplating Layer(Ni)
5	Electroplating Layer(Sn or SnPb)

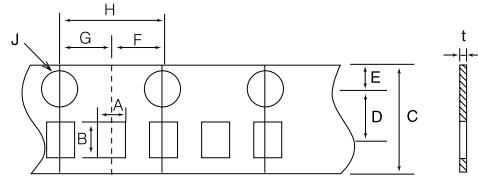
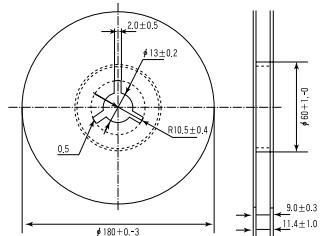
## CHIP DIMENSION



	L	W	T	L1, L2
1005	1.0 ; 0.1	0.5 ; 0.1	0.5 ; 0.1	0.2 ; 0.1
1608	1.6 ; 0.1	0.8 ; 0.1	0.8 ; 0.1	0.3 ; 0.1
2012	2.0 ; 0.1	1.2 ; 0.1	0.8 ; 0.1	0.4 ; 0.1
3216	3.2 ; 0.2	1.6 ; 0.2	1.0 ; 0.1	0.4 ; 0.1

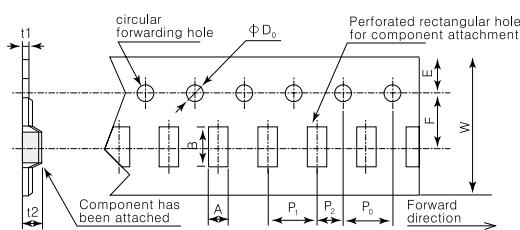
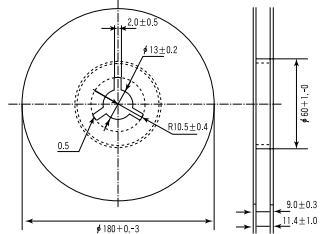
# Packaging

## Tape and Reel Packaging for Paper Package



Size	A	B	C	D	E	F	G	H	J	t	note
1608	1.0 ± 0.1	1.9 ± 0.1	8.0 ± 0.1	3.5 ± 0.05	1.75 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	4.0 ± 0.1	1.5+0.1-0.0	0.23 ± 0.02	paper
1005	0.62 ± 0.04	1.12 ± 0.04	8.0 ± 0.1	3.5 ± 0.05	1.75 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	4.0 ± 0.1	1.5+0.1-0.0	0.6 ± 0.05	paper

## Tape and Reel Packaging for Emboss Package



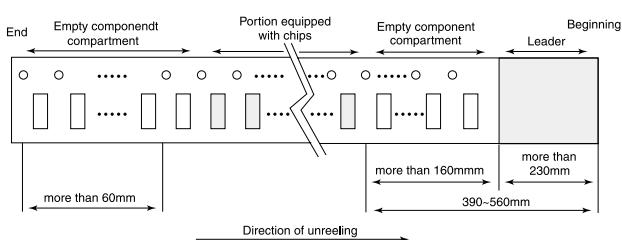
Size	A	B	W	F	E	P1	P2	P0	D0	t1	t2	note
3216	1.73 ± 0.1	3.56 ± 0.1	8.0+0.3-0.1	3.5 ± 0.05	1.75 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	4.0 ± 0.1	1.5+0.1-0.0	0.23 ± 0.02	1.14 ± 0.1	emboss
2012	1.45 ± 0.1	2.25 ± 0.1	8.0+0.3-0.1	3.5 ± 0.05	1.75 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	4.0 ± 0.1	1.5+0.1-0.0	0.23 ± 0.02	1.0 ± 0.1	emboss

## Structure of Taping

Taping must have leader and empty component compartment as shown in the following figure.

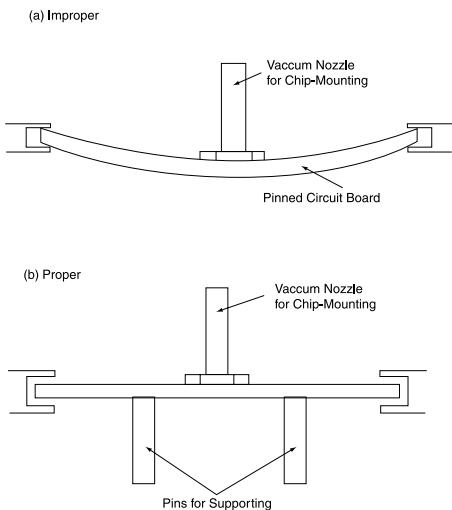
## Package Quantity

12,000(pcs/Reel) - 1005 size  
4,000(pcs/Reel) - 1608, 2012, 3216 size

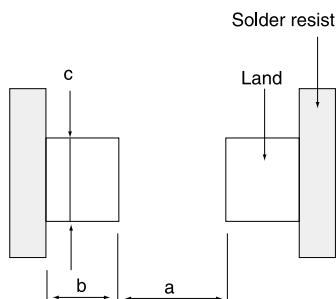


# SMT Process Characteristics

## Component Mounting



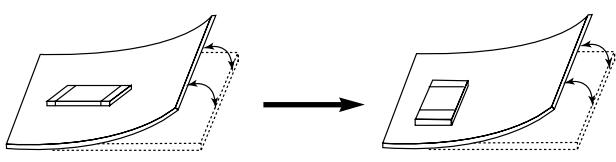
## Recommended Land Pattern



Chip size	a	b	c
1005(0402)	0.4	0.4 > 0.5	0.5
1608(0603)	0.6 > 0.8	0.6 > 0.7	0.6 > 0.8
2012(0805)	1.0 > 1.1	0.6 > 0.7	1.0 > 1.2
3216(1206)	2.1 > 2.3	1.0 > 1.1	1.3 > 1.4

## Component Layout

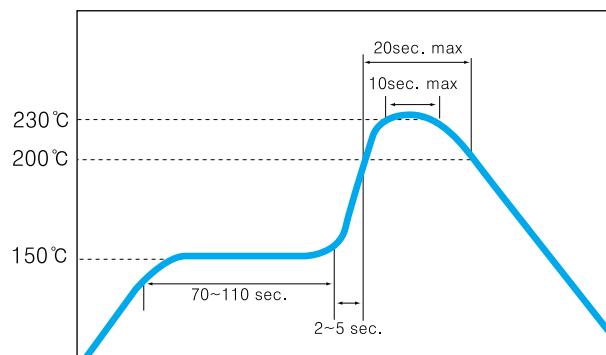
Locate the product horizontal to the direction at which bending is applied.



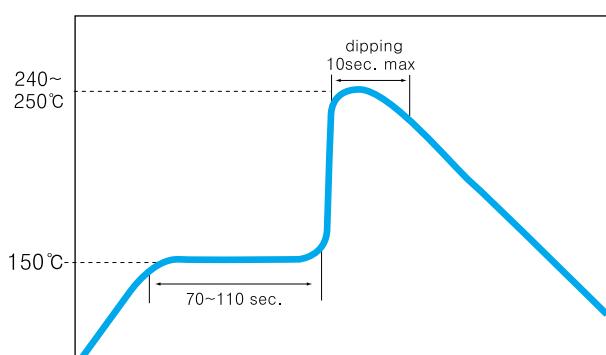
## Soldering

Hand soldering : 280°C max., 5sec max.

Reflow profile



Flow profile



## Solder and Flux

Solder : Eutetic solder recommended

Flux : Rosin based flux recommended

Halogen content 0.2 w% or less recommended